

In the Claims:

Please amend the claims as follows:

1. (currently amended) An apparatus comprising:
a photoconductor having a surface, the photoconductor provided with an aperture that extends through said photoconductor, and also provided with electroconductive material at least around edges of the aperture, and
an electroconductive material induced on said surface of the photoconductor, which material is connectable to a ground plane in order to conduct electrostatic discharges through the electroconductive material to the ground plane.
2. (canceled)
3. (canceled)
4. (currently amended) The apparatus according to claim 31, wherein the electroconductive material induced on said surface of the photoconductor is integrated with the photoconductor as a layer of electroconductive material for conducting light in the photoconductor and for shielding the light source against electrostatic pulses.
5. (previously presented) The apparatus according to claim 1, wherein the electroconductive material is metal and is connectable to the ground plane through the electroconductive material.
6. (previously presented) The apparatus according to claim 1, wherein the electroconductive material is realized on the surface of the photoconductor by an electroconductive film, or by inducing chemically or electrochemically.

7. (currently amended) An apparatus for shielding a component against electrostatic discharge comprising a light emitting diode and a photoconductor layer for conducting ~~the~~ light emitted by the light emitting diode, wherein the photoconductor layer includes electroconductive material, and that the electroconductive material is connectable to a ground plane in order to conduct electrostatic discharges from the photoconductor layer to the ground plane, further wherein the photoconductor layer is provided with an aperture that extends through said photoconductor layer, the light emitting diode at least partly placed in the aperture, inside the photoconductor layer, and the photoconductor layer also provided with an electroconductive material at least around the edges of the aperture.

8. (canceled)

9. (canceled)

10. (currently amended) The apparatus according to claim ~~9~~7, wherein ~~in the surface of the photoconductor layer, there~~ the photoconductor layer has a surface and wherein the electroconductive material of the photoconductor layer is integrated as a layer of electroconductive material for shielding ~~the~~ components against electrostatic pulses and for conducting the light emitted by the light emitting diode in the photoconductor layer.

11. (previously presented) The apparatus according to claim 7, wherein the light emitting diode is placed on a printed circuit board, the photoconductor layer is placed on the component side of the circuit board, and the electroconductive material is placed on that side of the photoconductor layer that faces away from the circuit board and the electroconductive material is connectable to the ground plane of the circuit board.

12. (previously presented) The apparatus according to claim 7, wherein the electroconductive material is metal, and it is connected to the ground plane by electroconductive material.

13. (previously presented) The apparatus according to claim 7, wherein the electroconductive material is realized on the surface of the photoconductor layer by an electroconductive film, or by inducing chemically or electrochemically.

14. (currently amended) The apparatus according to claim 7, ~~wherein on the~~further comprising a circuit board, there is a ~~and a keypad, wherein the~~ light emitting diode for is on said circuit board and configured to ~~illuminating~~illuminate the keypad, and ~~that the apparatus comprises a~~wherein the photoconductor layer ~~for conducting~~is configured to conduct the light emitted by the light emitting diode to a key of the keypad.

15. (canceled)

16. (canceled)

17. (previously presented) The method according to claim 21, wherein on the outermost surface of the photoconductor layer, facing away from the circuit board, there is integrated a layer of electroconductive material, which layer covers the whole surface of the photoconductor layer.

18. (previously presented) The method according to claim 17, wherein the electroconductive material is induced for shielding components of the circuit board against electrostatic pulses and for conducting the light emitted by the light emitting diode of the circuit board in the photoconductor layer.

19. (previously presented) The method according to claim 21, wherein the electroconductive material is metallized to the photoconductor layer and connected to the ground plane of the circuit board by electroconductive material.

20. (previously presented) The method according to claim 21, wherein the electroconductive material is realized in the photoconductor layer by an electroconductive film, or by inducing chemically or electrochemically.

21. (currently amended) A method comprising:

placing a light emitting diode on a printed circuit board,

arranging a photoconductor layer on a component side of the circuit board, the photoconductor layer provided with an aperture that extends through said photoconductor layer,

providing electroconductive material at least around edges of the aperture,

inducing an electroconductive material to the photoconductor layer, and

connecting the electroconductive material to a ground plane of the circuit board in order to conduct electrostatic discharges from the photoconductor layer to the ground plane of the circuit board.

22. (currently amended) An apparatus comprising:

means for providing a photoconductor having a surface, the photoconductor provided with an aperture that extends through said photoconductor, and also provided with electroconductive material at least around edges of the aperture, and

means for providing an electroconductive material induced on said surface of the means for providing a photoconductor, which material is connectable to a ground plane in order to conduct electrostatic discharges through the means for providing an electroconductive material to the ground plane.